

Title (en)
MICROELECTRONICS PACKAGE

Title (de)
MIKROELEKTRONISCHE PACKUNG

Title (fr)
BOITIER MICRO-ELECTRONIQUE

Publication
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Application
EP 97918585 A 19970411

Priority
• US 9706091 W 19970411
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Abstract (en)
[origin: WO9743787A1] A microelectronic package (100) suitable for high-frequency microelectronic devices (116) includes a base (102) which is at least partially conductive attached to an RF substrate (106) with a cavity formed at its center and a pattern of conductive paths (122) for providing interconnection from the inside to the outside of the package. The base may be metal or ceramic with a metal layer deposited thereon. A sealing cap (114) is attached to the RF substrate by a non-conductive adhesive, such as a polymer adhesive (112) of low temperature seal glass, to seal the package once the microelectronic device has been mounted inside.

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H01L 23/66

IPC 8 full level
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Citation (search report)
See references of WO 9743787A1

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